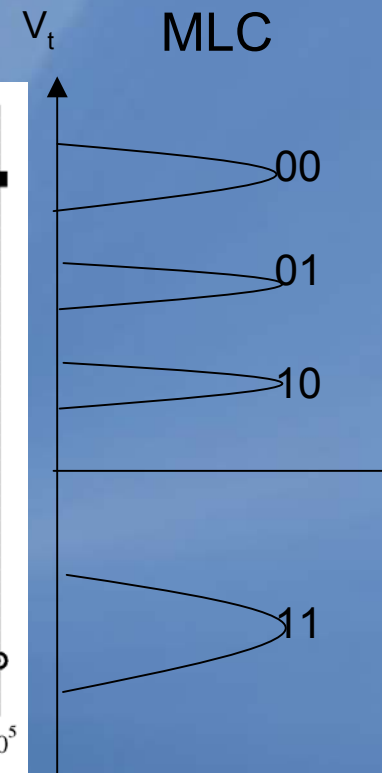
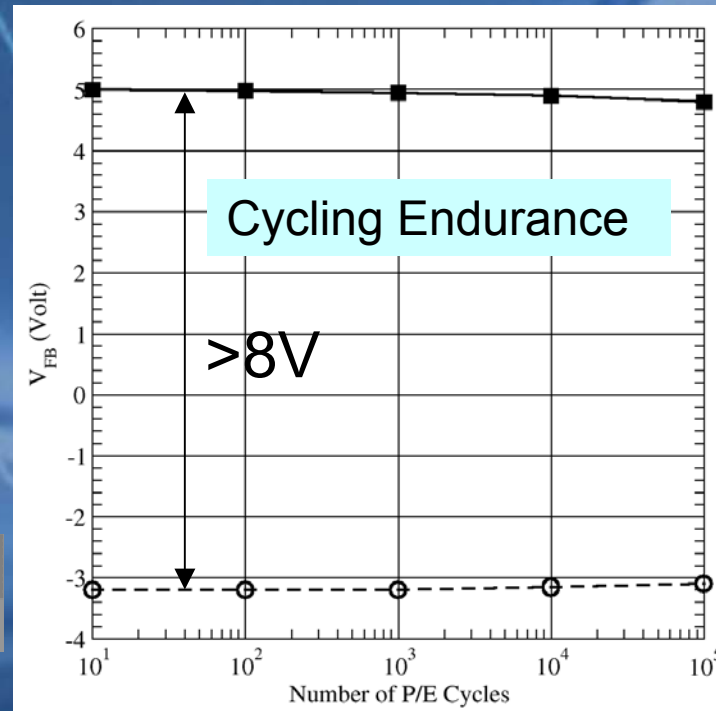
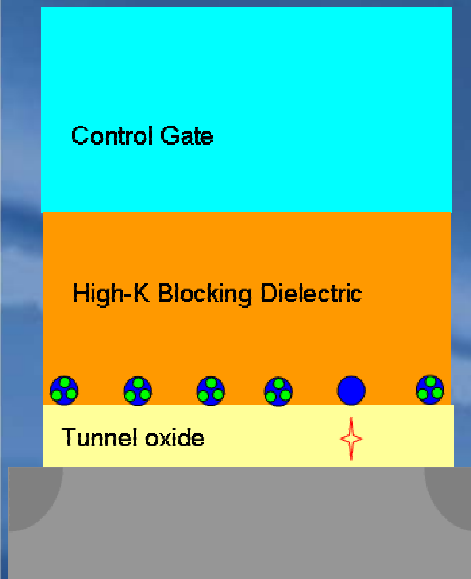


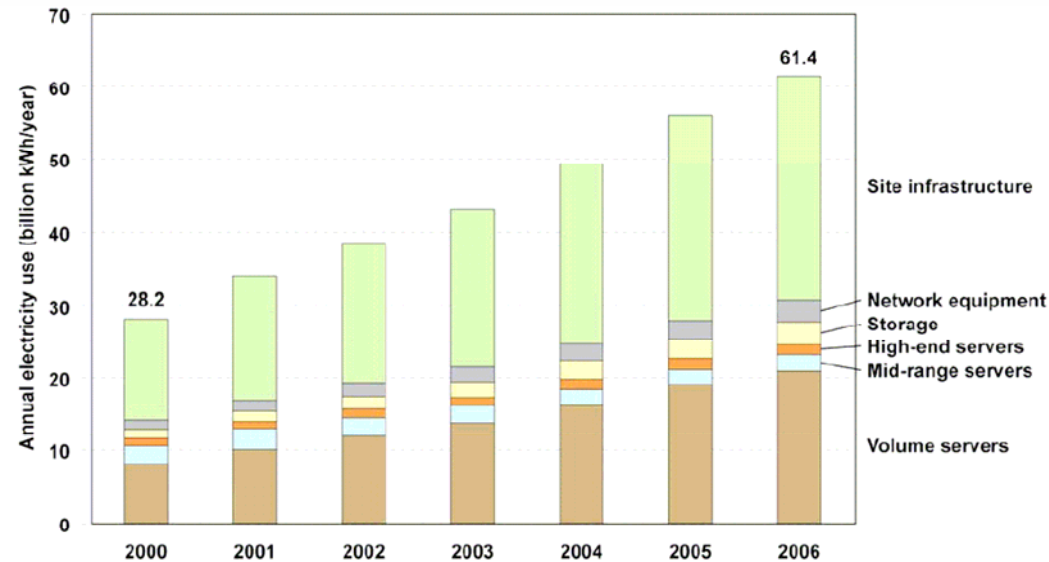
Colloidal Metal Nanocrystals for Multilevel Cell NAND Flash Memory with 100,000 Cycling Endurance

Jian Chen

Nanosys, Inc., Palo Alto, CA

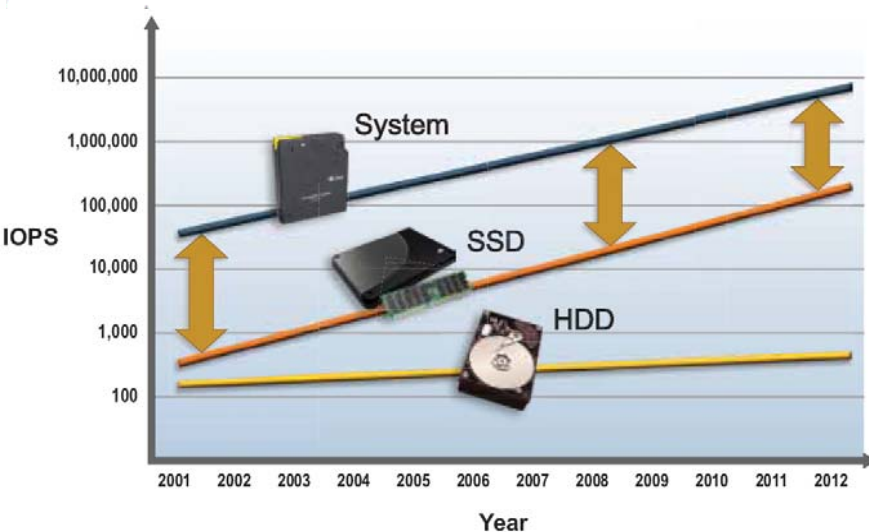


Electricity Consumption in Data Centers

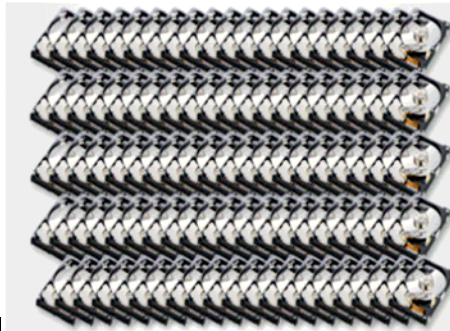


- In 2006, US data centers consume 61 billion kWh electricity, 1.5% of total US demand
- By 2011, demand will double to more than 100 billion kWh

SSDs Entering Enterprise Data Storage Much Lower Electricity Consumption



100 Enterprise HDDs

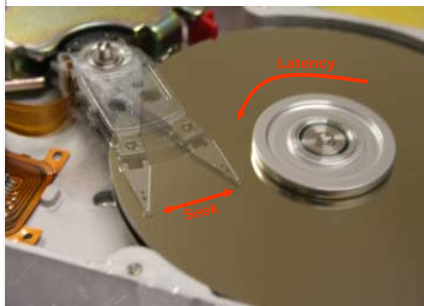
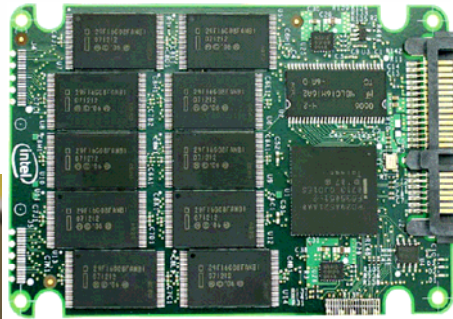


Capacity: 30TB
Performance: 30K IOPS
Cap/Op-X: \$55,000 – 1.2 kWh

Hybrid Storage Pool



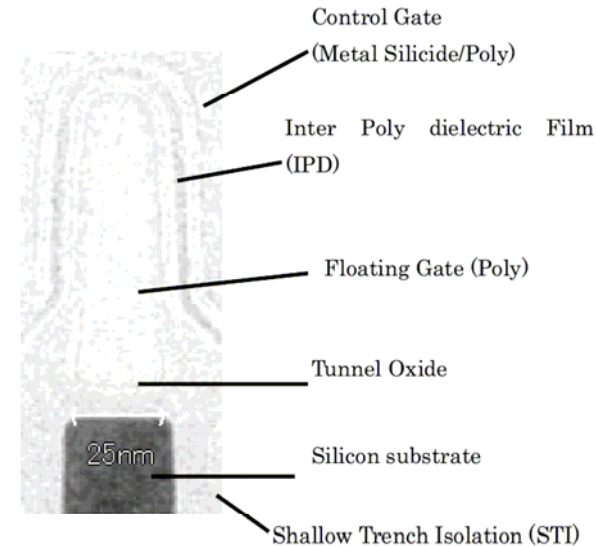
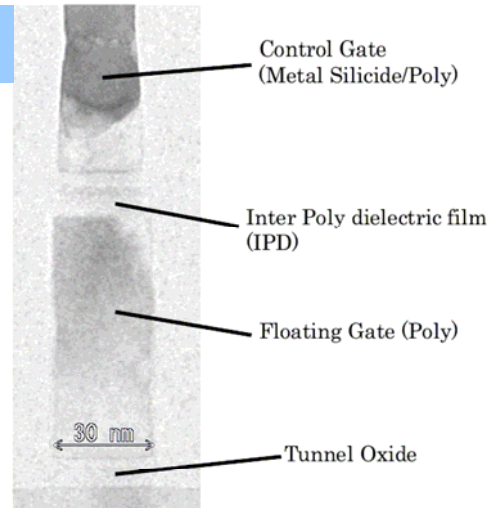
Capacity: 30TB
Performance: 30K IOPS
Cap/Op-X: \$18,000 – 0.392 kWh



https://www.sun.com/offers/details/ssd_sun_servers.html

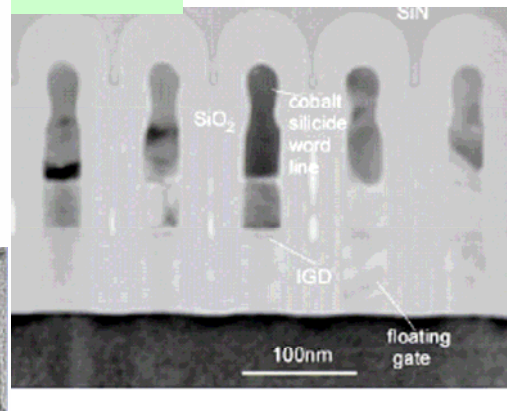
Progression of Poly-FG NAND Flash Technology

2xnm



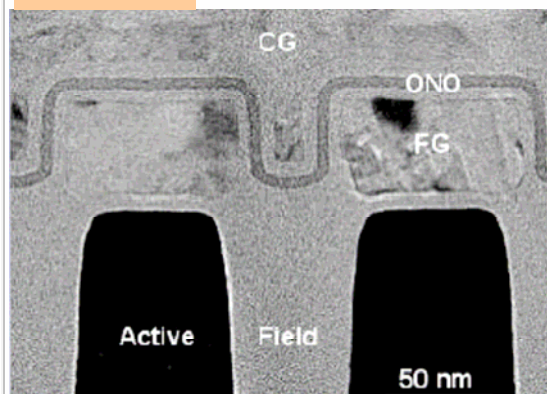
T. Kamigaichi, et. al., IEDM 2008.

4xnm

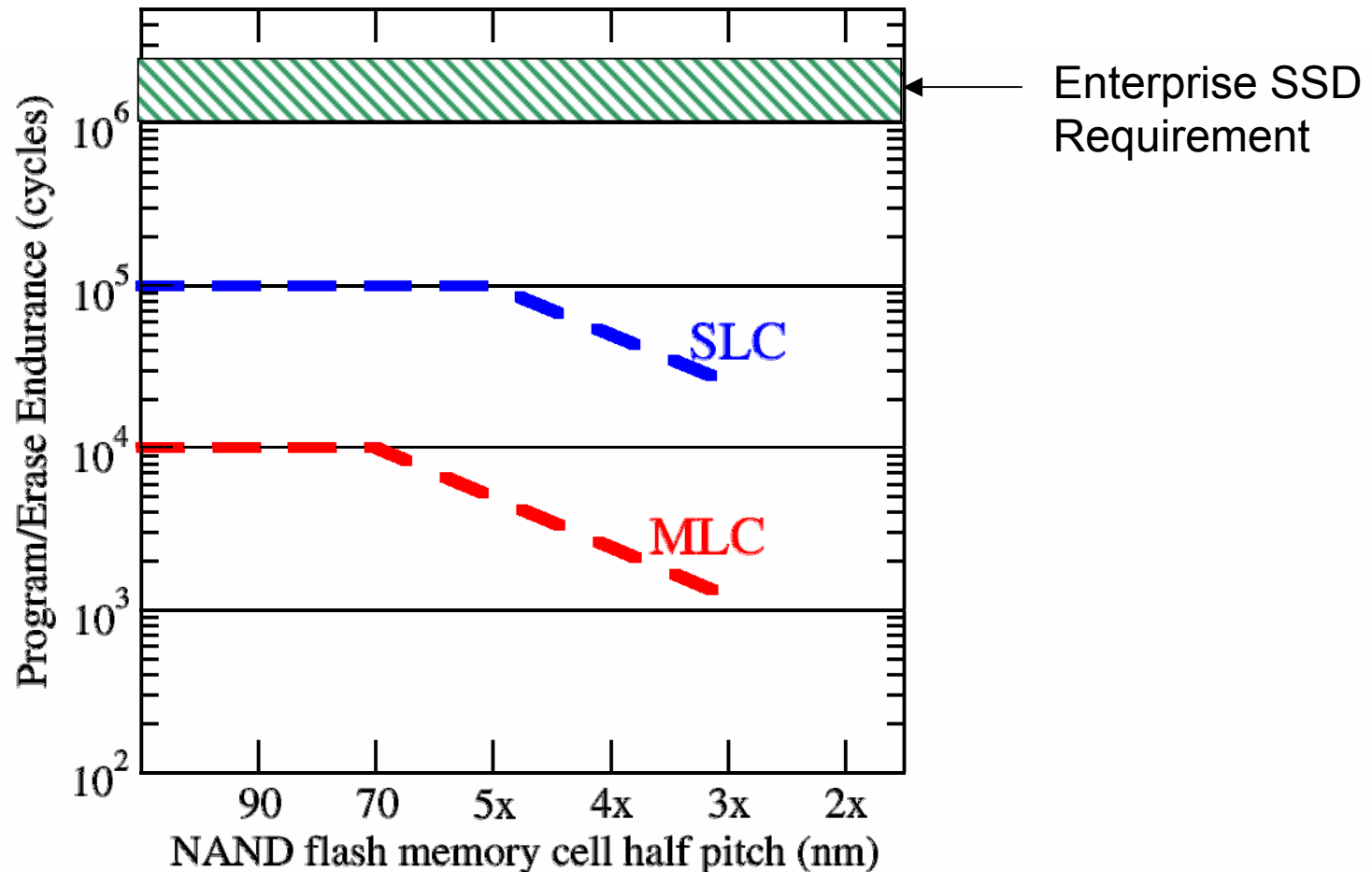


A. Fazio, Stanford, 11/2008

90nm



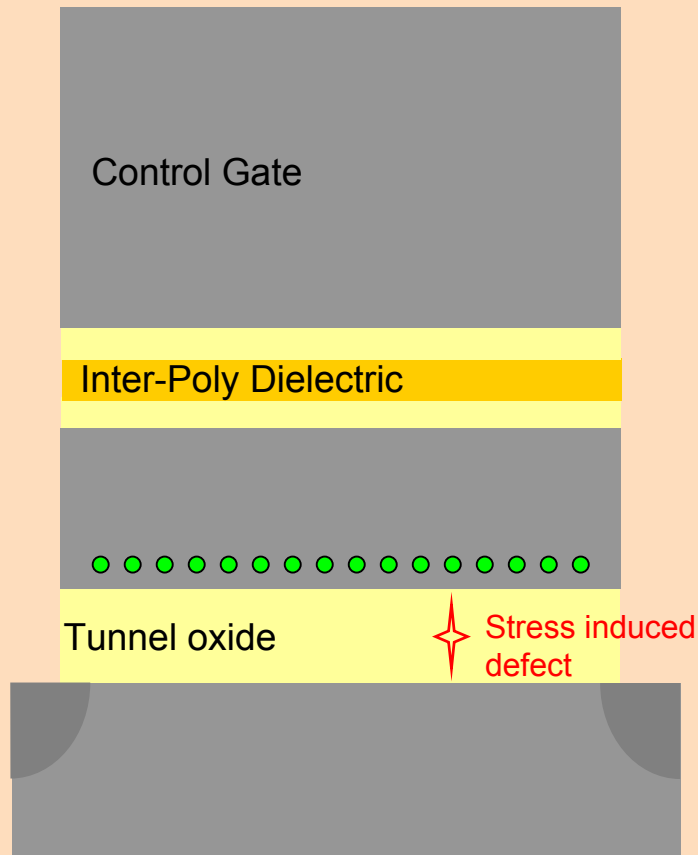
Degradation of Program/Erase Endurance at Smaller Technology Nodes



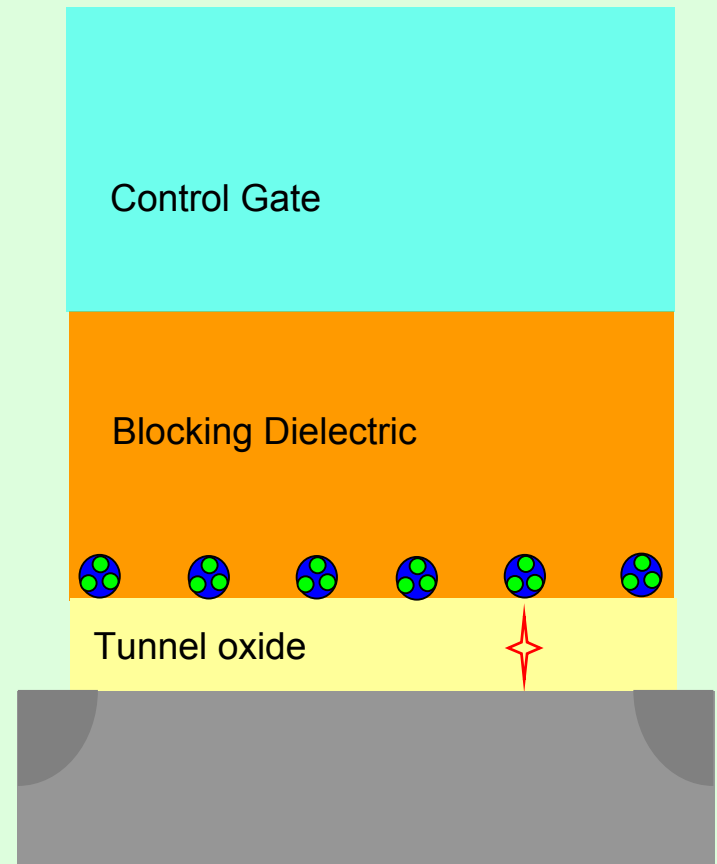
- SLC NAND with endurance $>\sim 100,000$ can meet the demand of enterprise SSD with the help from controllers (wear leveling, ECC, etc).

Discrete Charge Storage in Nanodots Offers Better P/E Cycling Endurance

Floating Gate



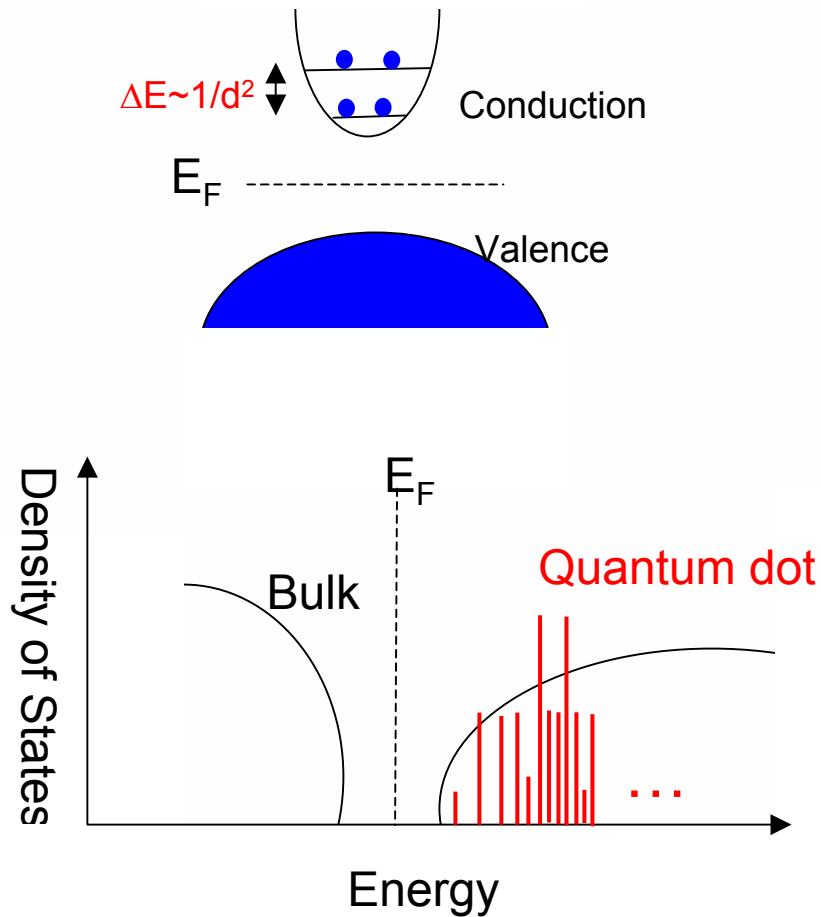
Nanodots



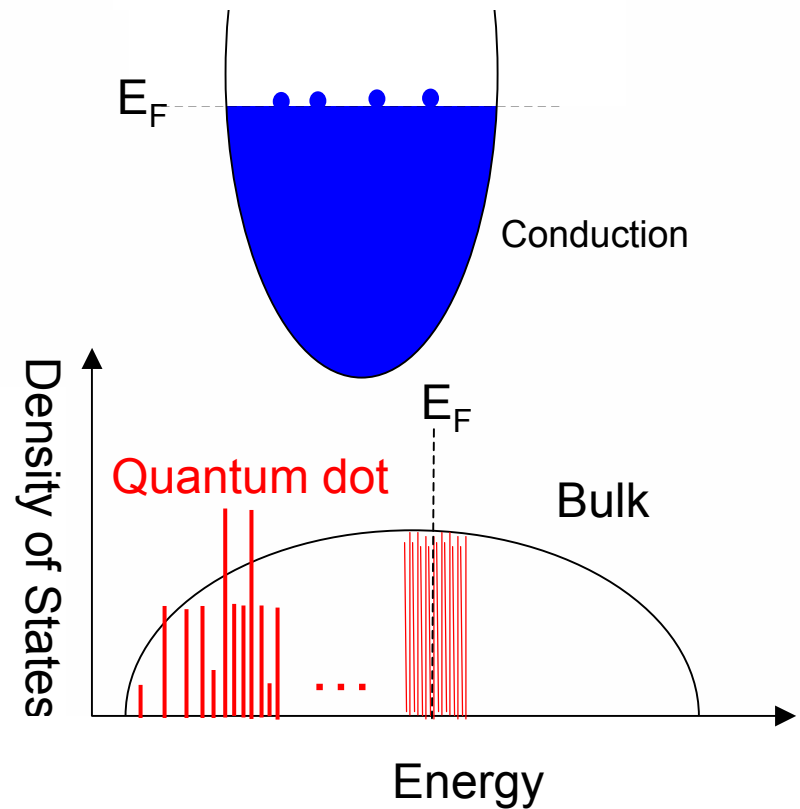
Why Metal Nanodots?

Much Higher DOS Than Semiconductor Dots

Semiconductor

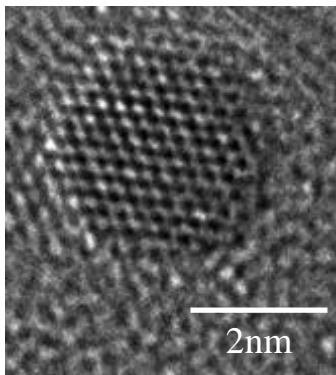
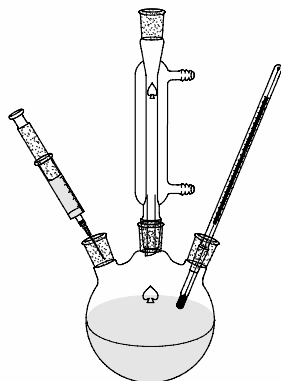


Metal

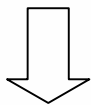
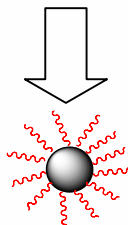


Highly Uniform and Tunable Nanodots Synthesized with Solution Chemistry

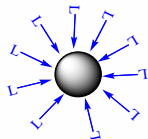
Dot
Synthesis



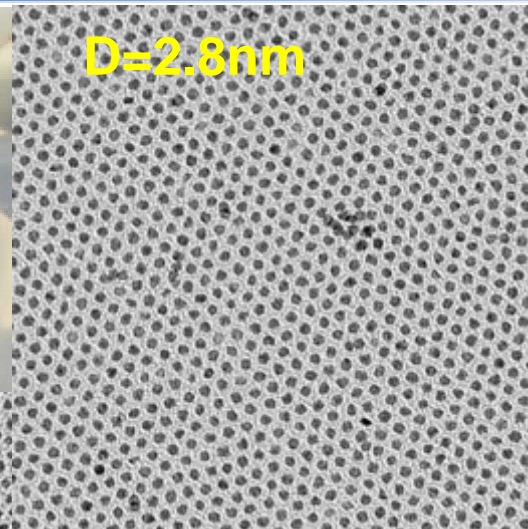
Dot with
Growth Ligand



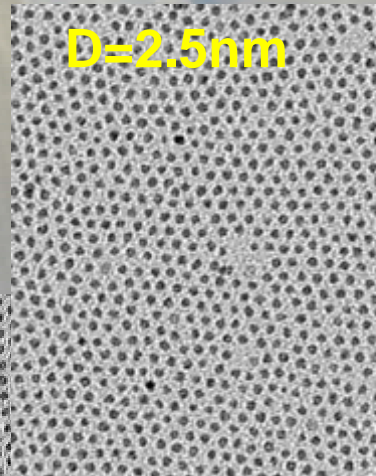
Exchanged with
new Ligand



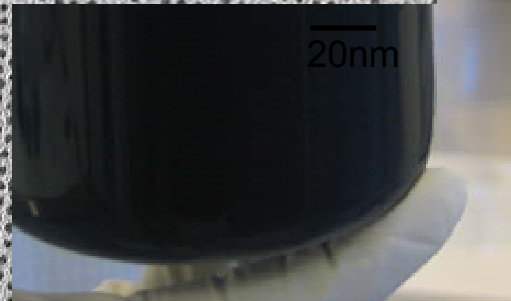
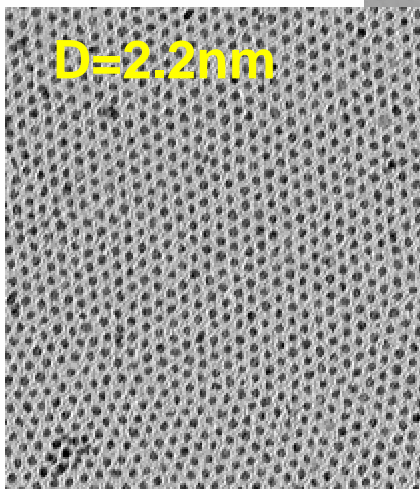
D=2.8nm



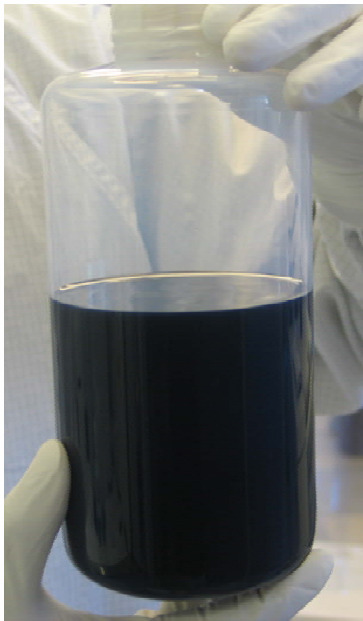
D=2.5nm



D=2.2nm

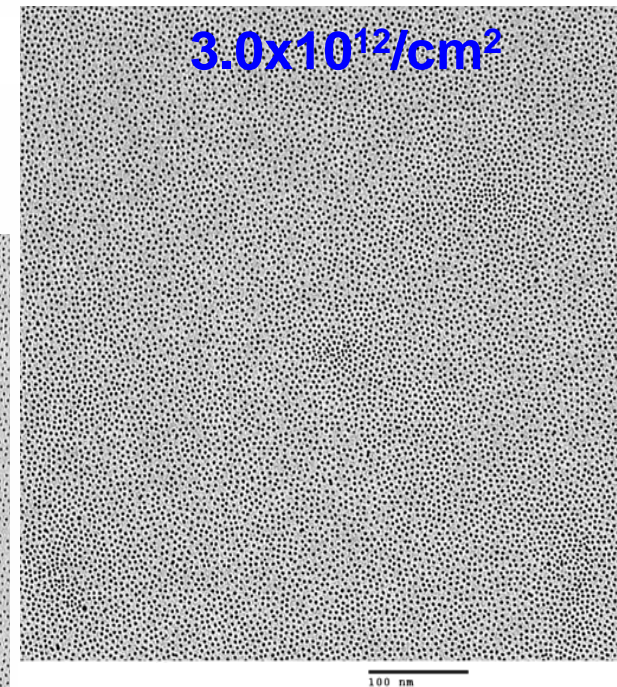
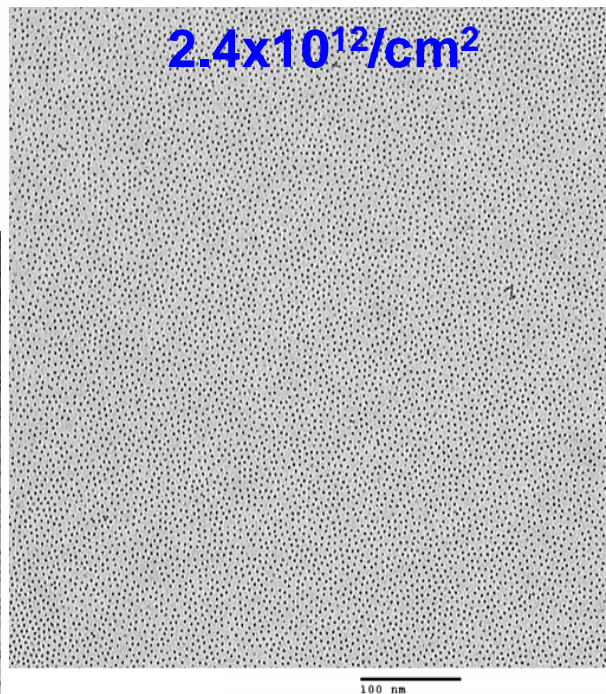
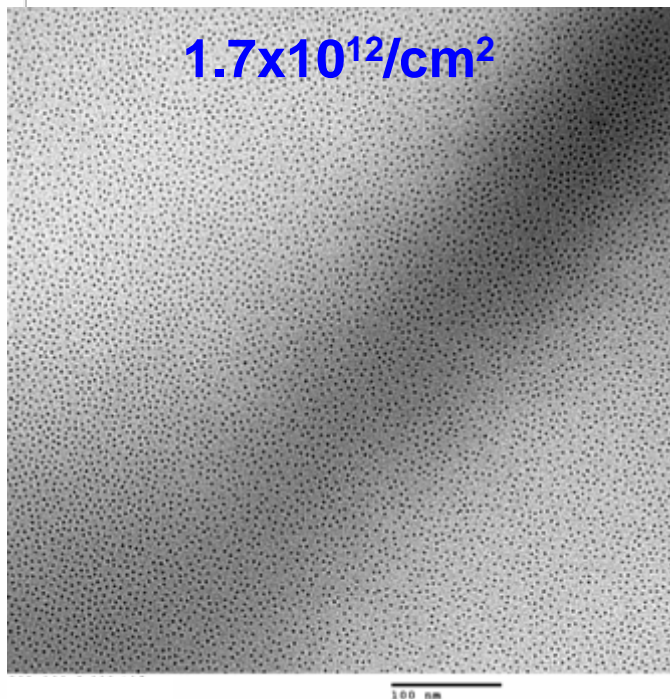
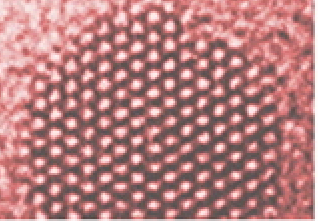


Nanodot Deposition using Spin-Coating



TEL Spin Coater Track

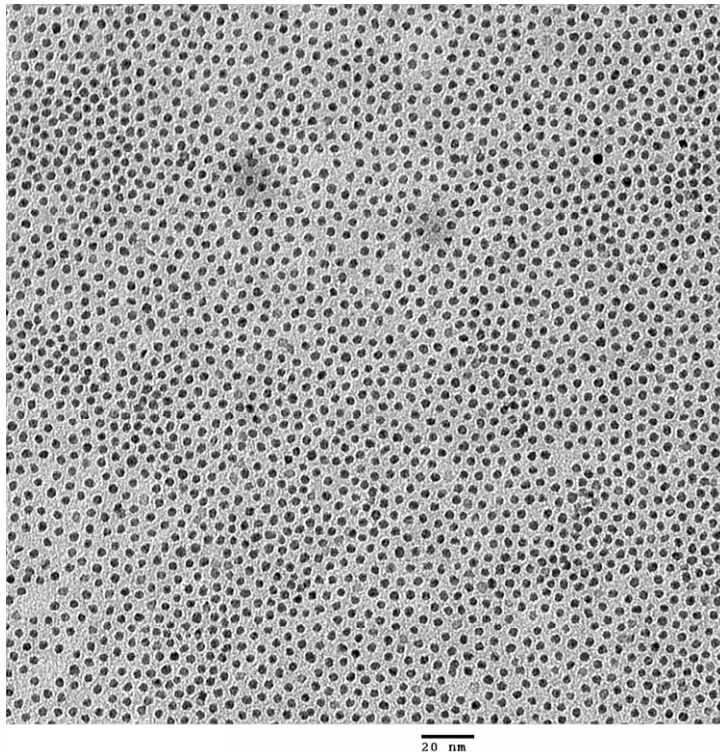
Adjustable Dot Density



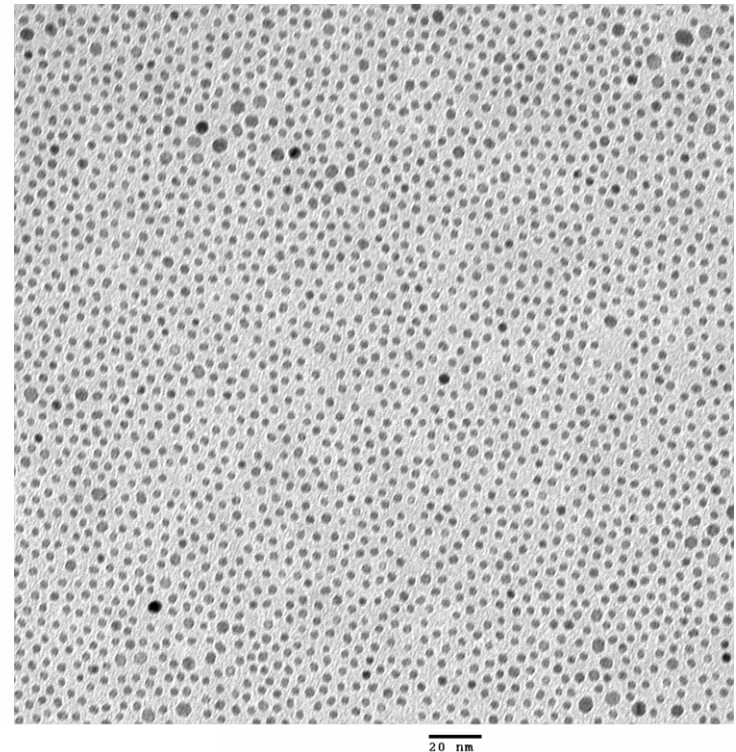
- By varying nanodot concentration and spin-coating conditions (e.g., wafer rotation speed), different nanodot densities on wafers can be obtained

Compatibility with CMOS Processing

As Deposited

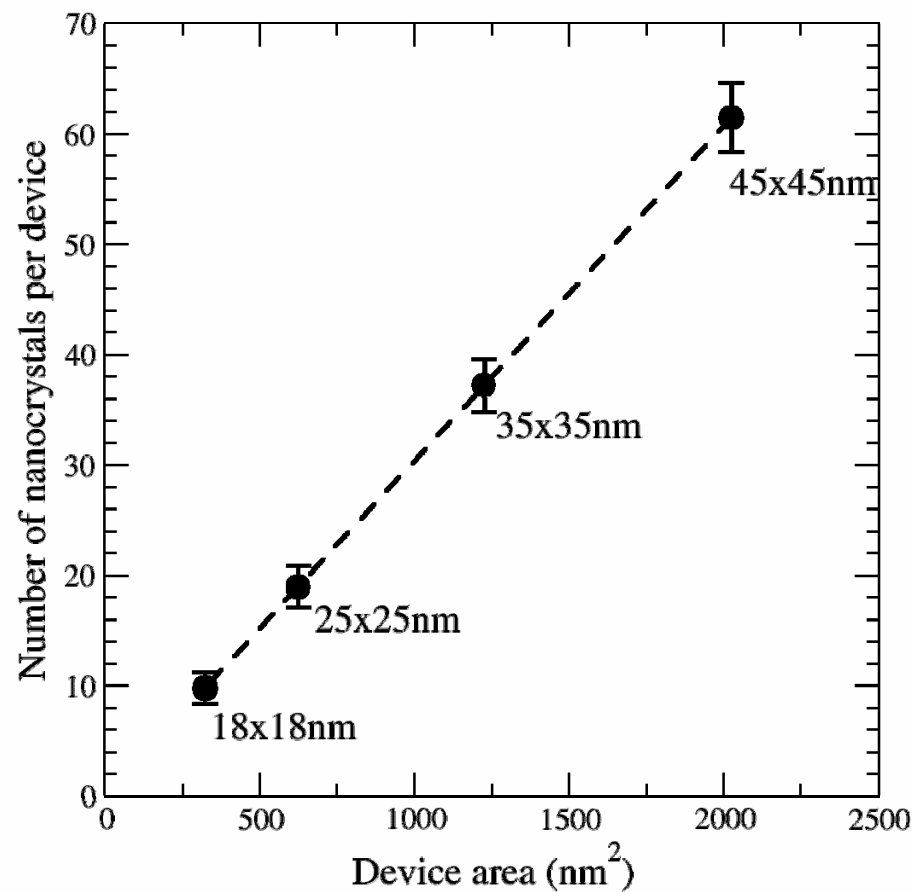
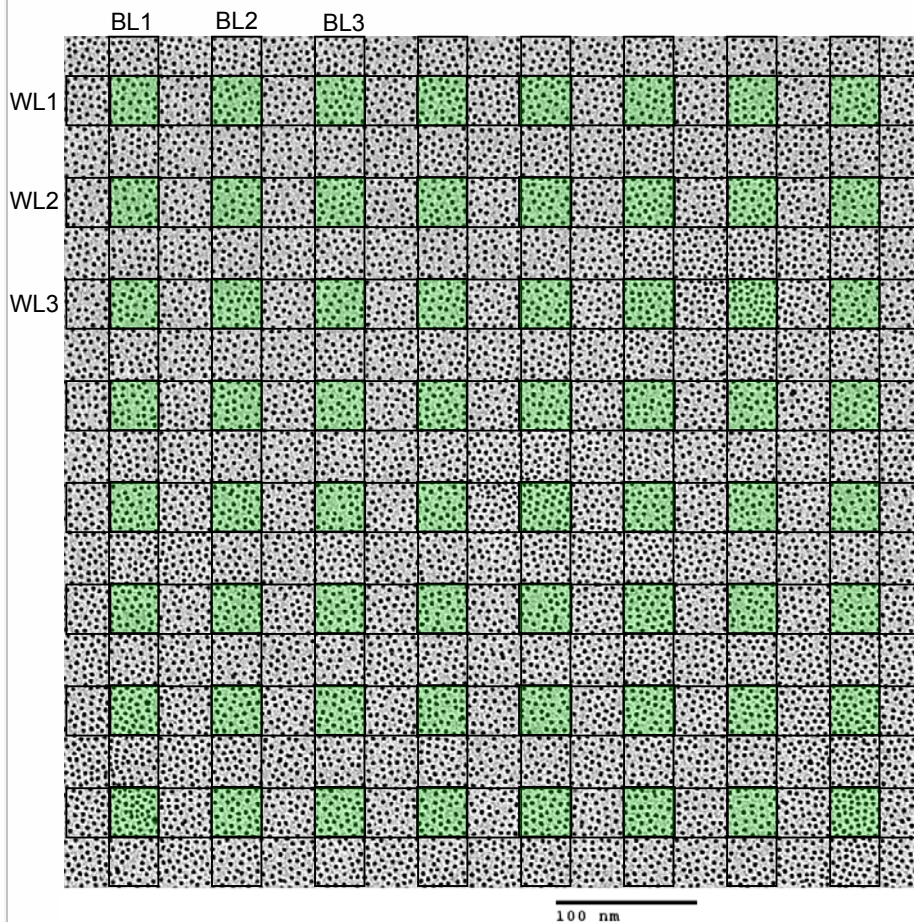


Post 950C RTP

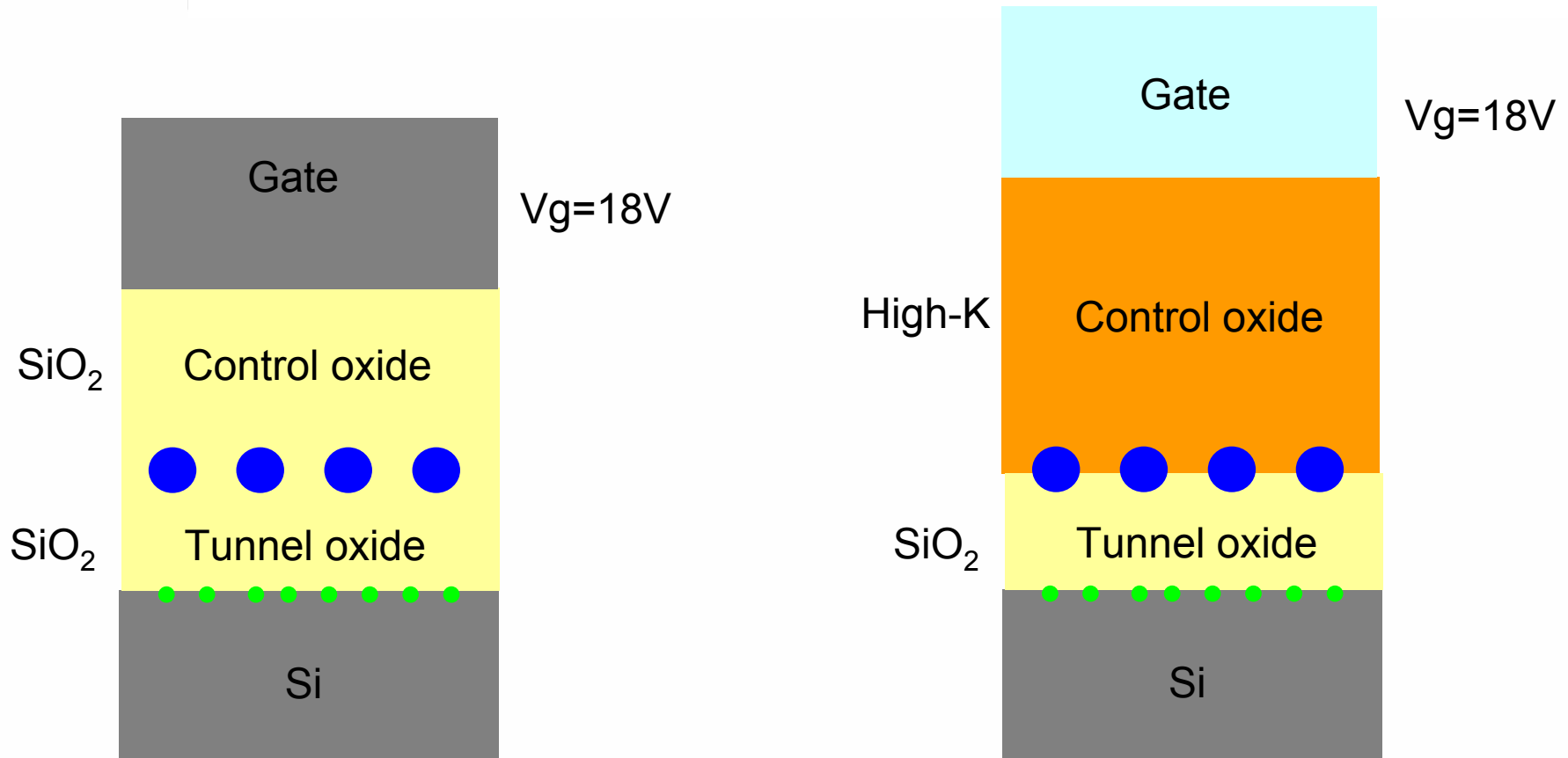


- High density of $\sim 3 \times 10^{12}$ dots/cm² obtained post 950C rapid thermal processing (source/drain implant activation)

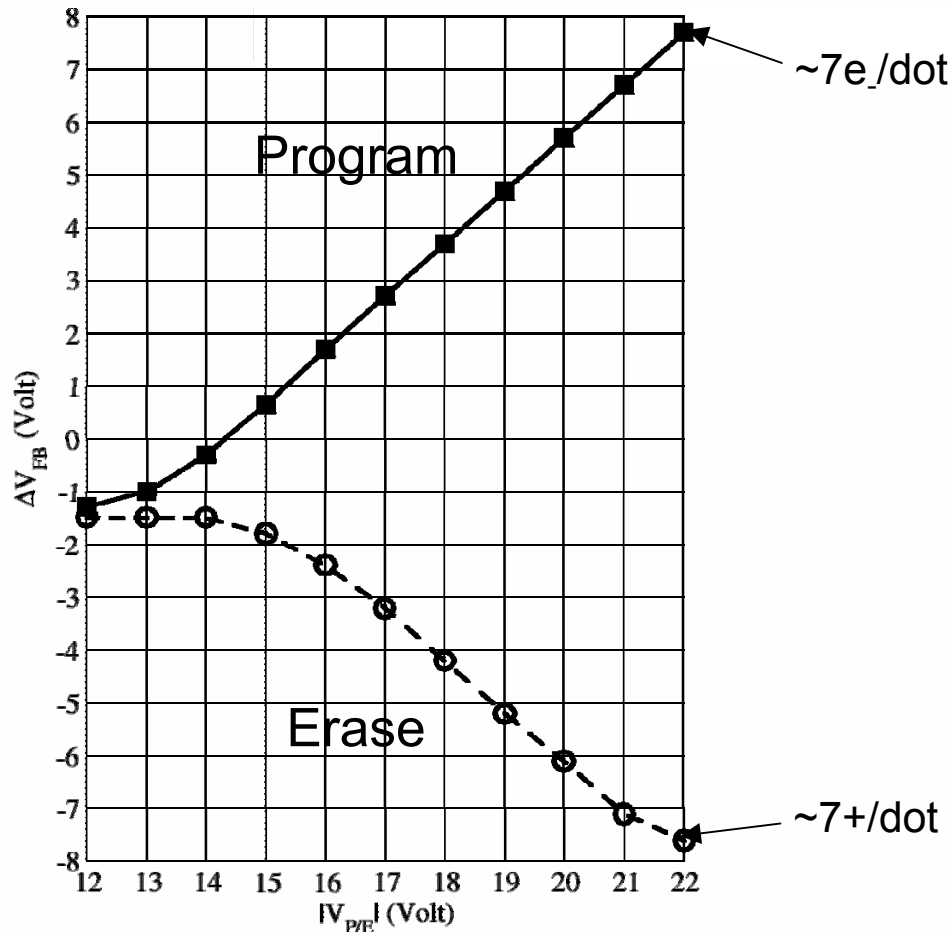
Highly Uniform Monolayer of Nanodots



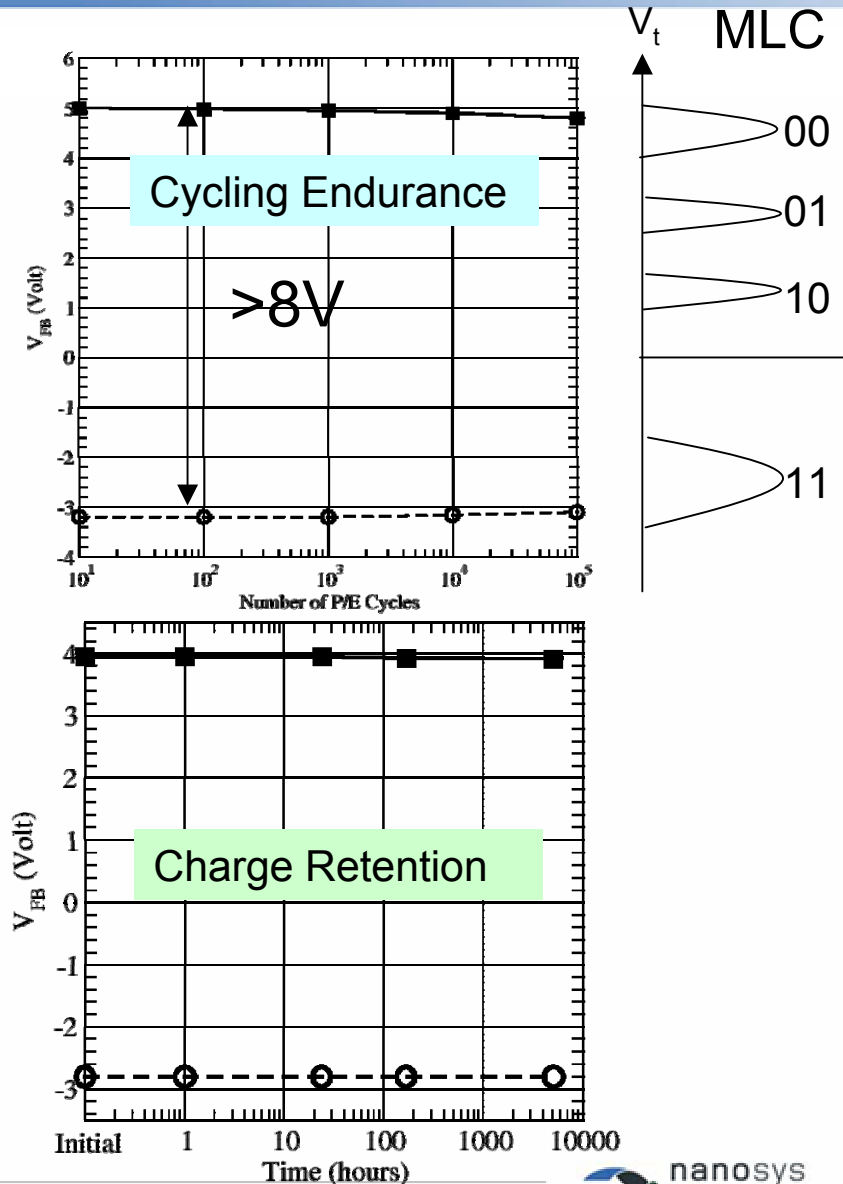
High-K Control Dielectric Increases Charge Storage Density for Nanodots



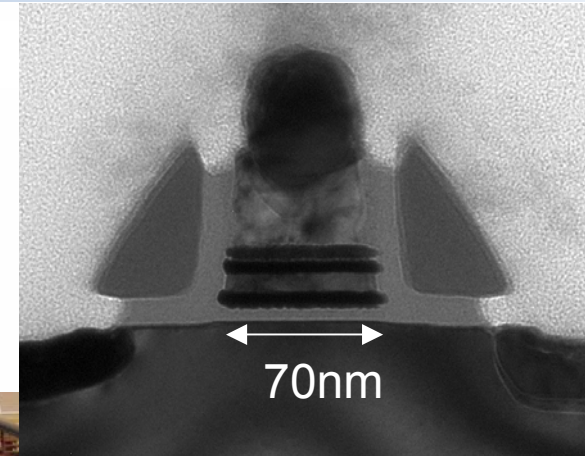
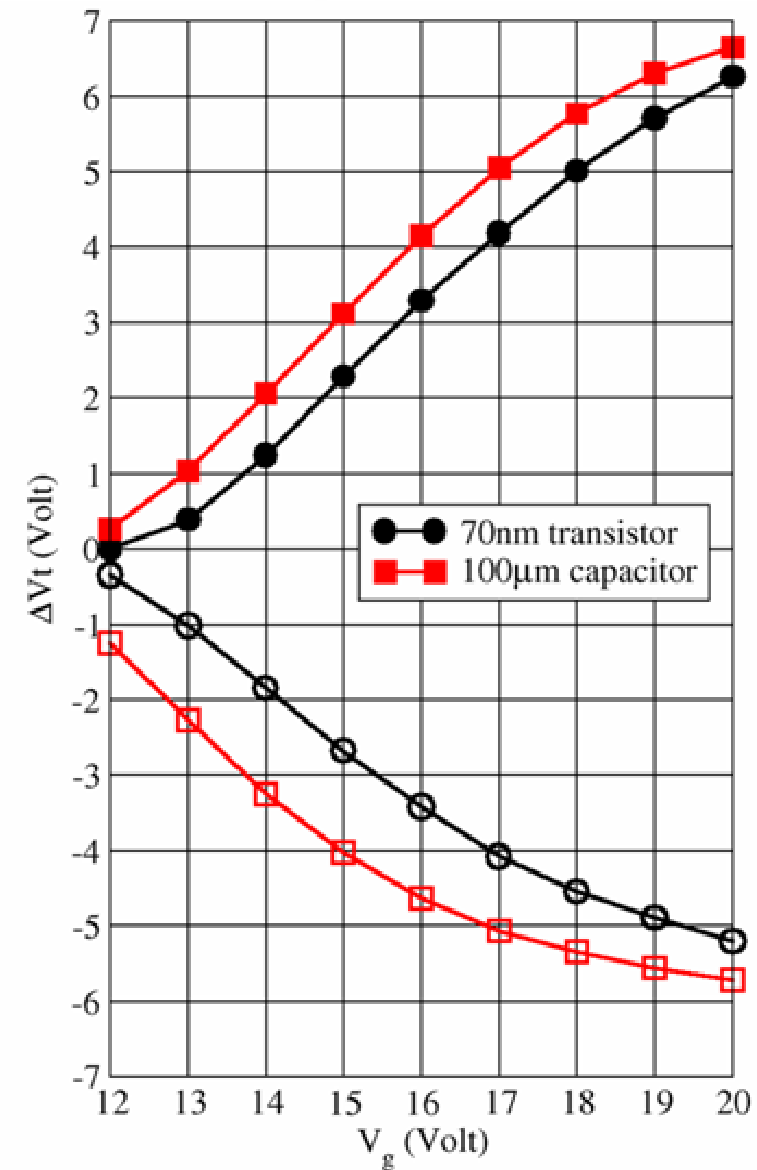
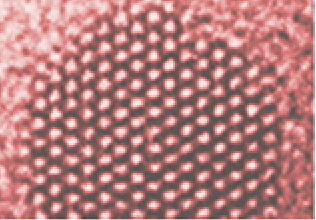
MOS Capacitor: Nanodot/High-K Offers Comparable Performance as FG/ONO



- $>8\text{V}$ P/E window, sufficient for MLC
- Compatible with 100,000 P/E cycles
- Excellent charge retention



Nanodot Flash Transistors



Conclusions

- Colloidal Metal Nanodots Combined with High-K Dielectric Offer an Alternative Charge-Storage NVM with Superior Endurance and Scalability
- Charge Storage: Poly FG → Metal Nanodots
 - Diameter: 2-3nm
 - Density: $>3 \times 10^{12}/\text{cm}^2$
 - Fully Compatible with CMOS Processing
- Control Dielectric: ONO → High-k
- Control Gate: Poly → Metal
- Nanodot/High-K Electrical Performance Sufficient for MLC & SSD Requirements
 - Program/Erase Window $>8\text{V}$
 - Endurance 100,000 P/E Cycles

